

# MECHANICAL CASE OUTLINE

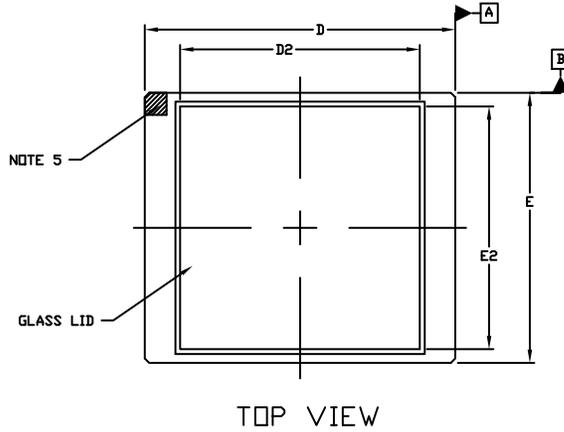
## PACKAGE DIMENSIONS

ON Semiconductor®



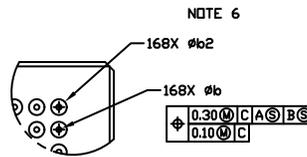
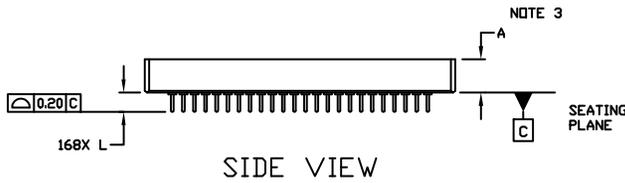
CPGA168, 35.50x30.50  
CASE 107DH-01  
ISSUE O

DATE 30 JUN 2011

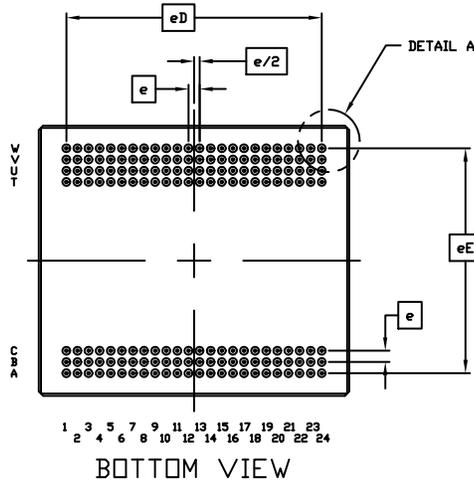


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION A INCLUDES THE PACKAGE BODY AND LID BUT DOES NOT INCLUDE HEATSINKS OR OTHER ATTACHED FEATURES.
4. DIMENSIONS D AND E DO NOT INCLUDE PROTRUSIONS. SUCH PROTRUSIONS SHALL NOT EXTEND MORE THAN 0.08 ON ANY SIDE. CORNERS AND EDGES OF THE PACKAGE MAY HAVE CHAMFERS.
5. PIN A1 IDENTIFICATION WILL BE IN THIS AREA. ID TYPE MAY CONSIST OF NOTCHES, METALLIZED MARKINGS, OR OTHER FEATURES.
6. THIS DIMENSION DEFINES THE MAXIMUM SIZE FOR THE PIN BRAZE PADS.



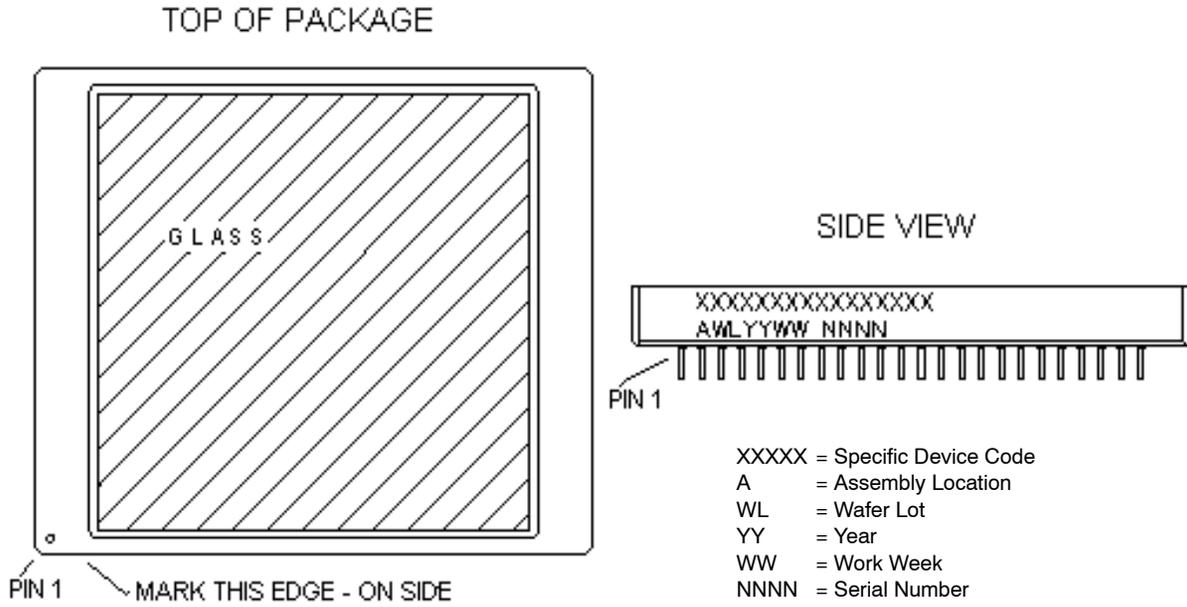
DIM	MILLIMETERS	
	MIN.	MAX.
A	3.37	4.13
b	0.25	0.35
b2	---	0.95
D	35.14	35.86
D2	27.40	REF
E	30.19	30.81
E2	27.40	REF
e	1.27	BSC
eD	29.21	BSC
eE	25.40	BSC
L	1.83	2.23



GENERIC MARKING  
DIAGRAM ON PAGE 2

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REFERENCE:		
DESCRIPTION:	CPGA168, 35.50 X 30.50	PAGE 1 OF 3

**GENERIC  
MARKING DIAGRAM**



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